L Number	Hits	Search Text	DB	Time stamp
-	334	29/829.ccls.	USPAT;	2002/12/10 15:46
	202	20/942 colo	US-PGPUB	00004040454540
-	302	29/842.ccls.	USPAT;	2002/12/10 15:46
_	763	29/874.ccls.	US-PGPUB USPAT:	2002/12/10 15:46
	700	20101 4.0013.	US-PGPUB	2002/12/10 15.40
-	387	29/884.ccls.	USPAT;	2002/12/11 14:06
			US-PGPUB	
-	69	29/884.ccls. and @py<2000 and (taper\$2 cone conical)	USPAT;	2002/12/11 14:04
	0.5	00/07/	US-PGPUB	
-	85	29/874.ccls. and @py<2000 and (taper\$2 cone conical)	USPAT;	2002/12/11 14:37
_	76	(29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not	US-PGPUB USPAT;	2002/12/11 14:07
	.0	29/884.ccls.	US-PGPUB	2002/12/11 14.07
-	687	29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 14:37
		cone conical)) not 29/884.ccls.)	US-PGPUB	
-	609	(29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 14:37
		cone conical)) not 29/884.ccls.)) and @py<2000	US-PGPUB	
-	131	((29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 14:38
		cone conical)) not 29/884.ccls.)) and @py<2000) and	US-PGPUB	
_	52	method.ti. (((29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 15:12
-	52	cone conical)) not 29/884.ccls.)) and @py<2000 and (taper\$2	US-PGPUB	2002/12/11 15:12
		method.ti.) and (printed adj circuit adj board pc adj board	00-1 01 05	
		substrate wafer laminat\$2)		
-	1077	216/41, 44.ccis. and @py<2000	USPAT;	2002/12/11 15:11
			US-PGPUB	
-	808	(216/41, 44.ccls. and @py<2000) and (printed adj circuit adj	USPAT;	2002/12/12 15:50
	70	board pc adj board substrate wafer laminat\$2)	US-PGPUB	
-	79	((216/41, 44.ccls. and @py<2000) and (printed adj circuit adj board pc adj board substrate wafer laminat\$2)) and corros\$3	USPAT; US-PGPUB	2002/12/11 15:14
_	71	((216/41, 44.ccls. and @py<2000) and (printed adj circuit adj	USPAT;	2002/12/12 13:30
		board pc adj board substrate wafer laminat\$2)) and method.ti.	US-PGPUB	2002/12/12 10:00
		and (corros\$3 salt salin\$3)		
-	1	6171164.pn.	USPAT;	2002/12/11 15:41
	_		US-PGPUB	
-	1	5391259.pn.	USPAT;	2002/12/12 13:34
Ì	1	5302238.pn.	US-PGPUB	2002/42/42 44:02
-	,	5502256.pn.	USPAT; US-PGPUB	2002/12/12 14:02
_	385	257/775.ccls.	USPAT;	2002/12/12 14:03
	000	25//// 5.55/5.	US-PGPUB	2002/12/12 14:00
-	237	257/775.ccls. and @py<2000	USPAT;	2002/12/12 14:24
		J.,	US-PGPUB	
-	43	(257/775.ccls. and @py<2000) and method.ti.	USPAT;	2002/12/12 14:24
		100 == 1	US-PGPUB	
-	264	438/754.ccls.	USPAT;	2002/12/12 14:49
	62	438/754.ccls. and @py<2000 and method.ti.	US-PGPUB	2002/12/12 14:50
-	02	430//34.ccis. and @py\2000 and method.ti.	USPAT; US-PGPUB	2002/12/12 14:50
_	96	438/673.ccls.	USPAT;	2002/12/12 15:44
			US-PGPUB	2002, 12, 12, 10, 11
-	31	438/673.ccls. and @py<2000 and method.ti.	USPAT;	2002/12/12 15:47
	:		US-PGPUB	
-	567	438/669.ccls.	USPAT;	2002/12/12 15:44
	004	400/000	US-PGPUB	000040404545
•	201	438/669.ccls. and @py<2000 and method.ti.	USPAT;	2002/12/12 15:49
_	185	(438/669.ccls. and @py<2000 and method.ti.) and (printed adj	US-PGPUB USPAT;	2002/12/12 16:10
_	103	circuit adj board pc adj board substrate wafer laminat\$2) not	US-PGPUB	2002/12/12 10.10
		((257/775.ccls. and @py<2000) and method.ti.) not	JO-F GF UB	
		(438/754.ccls. and @py<2000 and method.ti.) not		
		(438/673.ccls. and @py<2000 and method.ti.)		
-	789020	printed adj circuit adj board pc adj board substrate wafer	USPAT;	2002/12/12 16:26
1		laminat\$2) (plated plating) (rhodium palladium gold	US-PGPUB	

-	909334	(printed adj circuit adj board pc adj board substrate wafer	USPAT;	2002/12/12 16:22
		laminat\$2) (plated plating) (rhodium palladium gold) and (etch remov\$2) anisotropic (taper\$3 cone conical)	US-PGPUB	
-	16041	(printed adj circuit adj board pc adj board substrate wafer) and	USPAT;	2002/12/12 16:26
-	772	((plated plating) same (rhodium palladium gold)) ((printed adj circuit adj board pc adj board substrate wafer)	US-PGPUB USPAT:	2002/12/12 16:28
		and ((plated plating) same (rhodium palladium gold))) and (etch remov\$2) and anisotropic and (taper\$3 cone conical point\$2 sharp)	US-PGPUB	
-	159	(((printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))) and (etch remov\$2) and anisotropic and (taper\$3 cone conical point\$2 sharp)) and (contact bump\$2 electrode) and method.ti.	USPAT; US-PGPUB	2002/12/12 16:32
		and @py<2000		